FINAL PRODUCT/PROCESS CHANGE NOTIFICATION # 20398

Generic Copy

Issue Date: 12-Mar-2014

TITLE: Assembly and Test site transfer from Kanto Sanyo Semiconductors Co., Ltd to ON Semiconductor SGC Industries Malaysia Sdn Bhd. (SBN) and Package change from MSOP8 (150mil) to Micro8.

PROPOSED FIRST SHIP DATE: 12-Jun-2014

AFFECTED CHANGE CATEGORY(S): Assembly /Test site and PKG change

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact your local ON Semiconductor Sales Office or <Tomoya.Sato@onsemi.com>
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SAMPLES: Contact your local ON Semiconductor Sales Office or <Takashi.Asami@onsemi.com>

ADDITIONAL RELIABILITY DATA: Available
Contact your local ON Semiconductor Sales Office or <Kazutoshi.Kitazume@onsemi.com>

NOTIFICATION TYPE:

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <quality@onsemi.com>.

DESCRIPTION AND PURPOSE:

As a part of restructuring of semiconductor production infrastructure, Hanyu plant of Kanto Sanyo Semiconductors Co., Ltd will be closed at the end of June, 2014 and have been started preparation for end of production.

In order to continue supply of applicable products under this condition, the products and the equipments will be transferred to ON Semiconductor SGC Industries Malaysia Sdn Bhd. (SBN).
The package will be changed from MSOP8 (150mil) to Micro8 which have been manufactured as standard product in SBN. This package change affects changing for the lead width and lead thickness. The marking name will NOT be changed though the product name will be changed.

The product name

Current Product Name	Alternative Product Name
LE25CB643TT-TLM-E (MSOP8(150mil))	**LE25CB643TT-BH (Micro8)**

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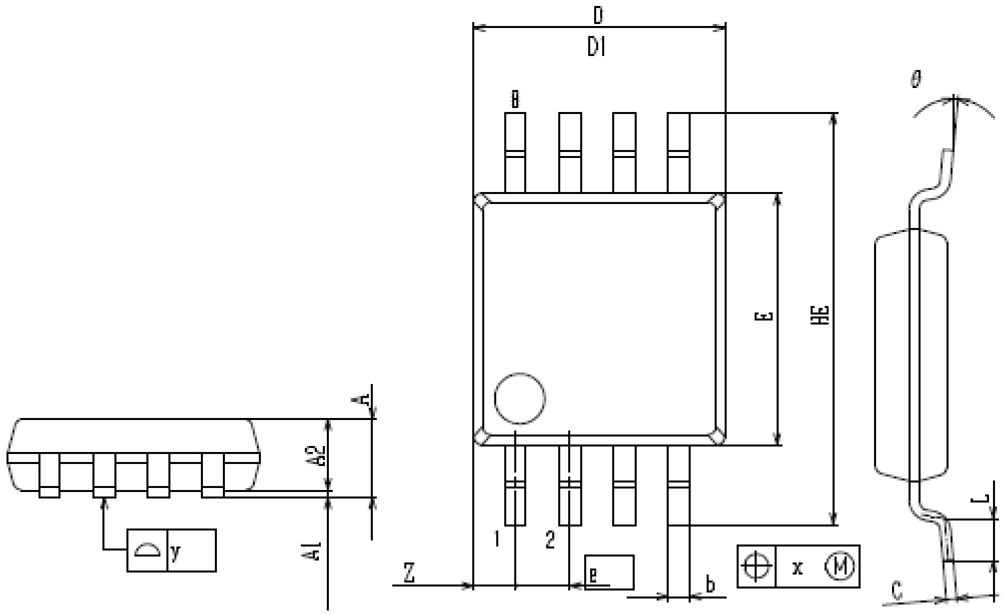
Package size comparison between MSOP8 (150mil) and Micro8



Current

	MSOP8(150mil)		
symbol	MIN.	NOM.	MAX
D			3.40
D1	2.9	3.0	3.1
A			1.10
A1	0.03	0.08	0.18
A2		(0.85)	
e		0.65	
L	0.3	0.5	0.7
b	0.21	0.25	0.30
c	0.105	0.125	0.195
x		0.10	
y		0.10	
HE	4.65	4.90	5.15
E	2.9	3.0	3.1
θ	0.00		10.00
Z		(0.53)	

After Transfer

(Unit: mm)

	Micro8		
symbol	MIN.	NOM.	MAX.
D			
D1	2.90	3.00	3.10
A			1.10
A1	0.05	0.08	0.15
A2			
e		0.65	
L	0.40	0.55	0.70
b	0.25	0.33	0.40
c	0.13	0.18	0.23
x		0.08	
y		0.038	
HE	4.75	4.90	5.05
E	2.90	3.00	3.10
θ			
Z			

The item in red box is changed before and after

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RELIABILITY DATA SUMMARY:

Reliability Test Results: LE25CB643TT-TLM-E

Test Items		Test Condition	Test Time		Failure
Temperature Humidity Bias	※	Ta=85℃,RH=85%,VCC=Recommended	1000	h	0
Temperature Humidity Storage	※	Ta=85℃,RH=85%	1000	h	0
Temperature Cycle	※	Ta=-65℃ 30min. ⇔ Ta=150℃ 30min.	200	Cycle	0
Pressure Cooker	※	Ta=121℃,RH=100% 2.03x10^5Pa	200	h	0
High Temperature Storage		Ta=150℃	1000	h	0

Notice) The test items with ※ mark are put into operation after the reflow soldering (at 255°C for 30s,3times).

ELECTRICAL CHARACTERISTIC SUMMARY:

There are no changes for electrical characteristic. Because this is package change only.

CHANGED PART IDENTIFICATION:

The suffix of the last part of the part number changes from “-TLM-E” to “-BH”.

List of affected General Parts:

LE25CB643TT-TLM-E